

APR 25 2005

1270.43264X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: H. KOMATSU

Application No.: 10/701,448

Filed: November 6, 2003

For: PHOTOSENSITIVE RESIN COMPOSITION, PROCESS FOR
FORMING RELIEF PATTERN, AND ELECTRONIC
COMPONENT

Art Unit: 1752

Examiner: H. Le

Confirmation No. 7624

AMENDMENT

Mail Stop: Amendment - Fee
 Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450

April 25, 2005

Sir:

In response to the Office Action mailed November 23, 2004, the period for response having been extended for two months by the attached Petition for Extension of Time, please amend the above-identified application as listed in the following, and as set forth on the following pages:

AMENDMENTS TO THE CLAIMS; and

REMARKS are included following the amendments.